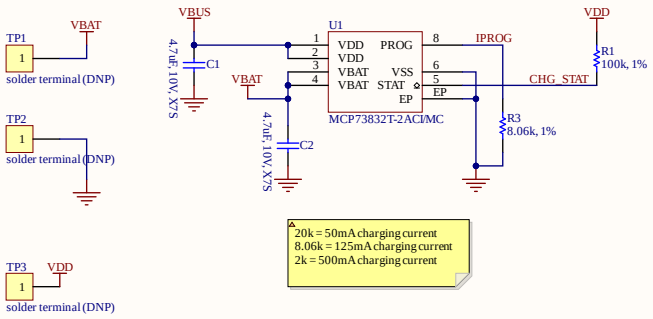
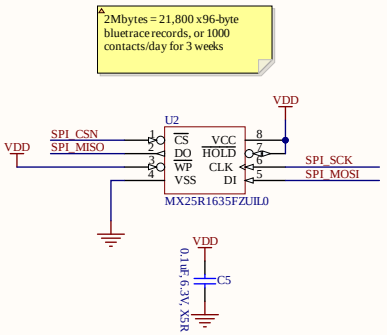
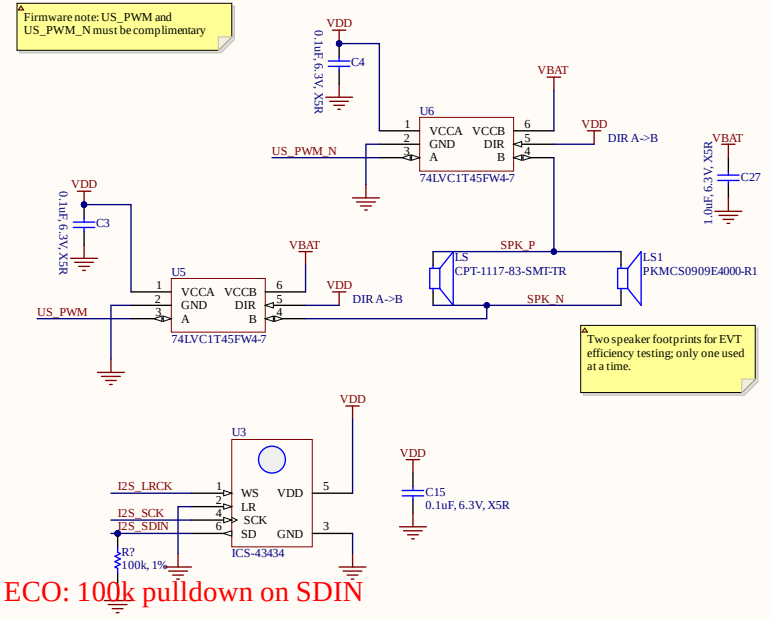
Charger

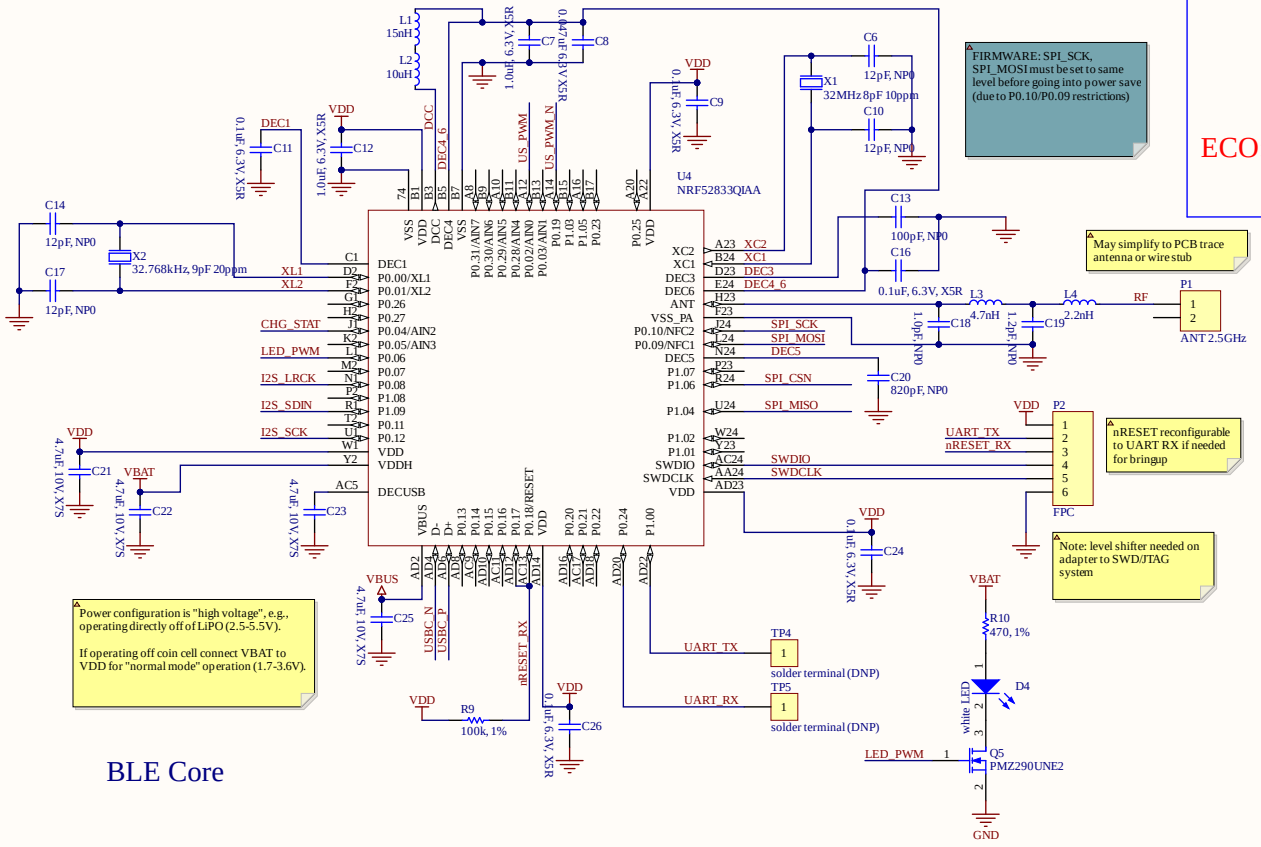


Contact Trace ROM



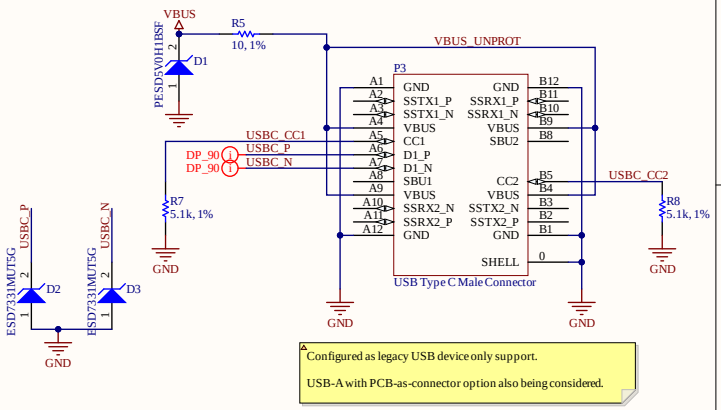
Near Ultrasound Option





BLE Core

USB-C Option



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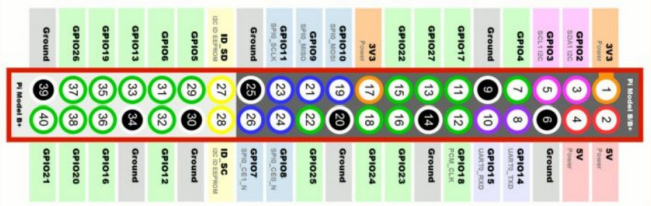
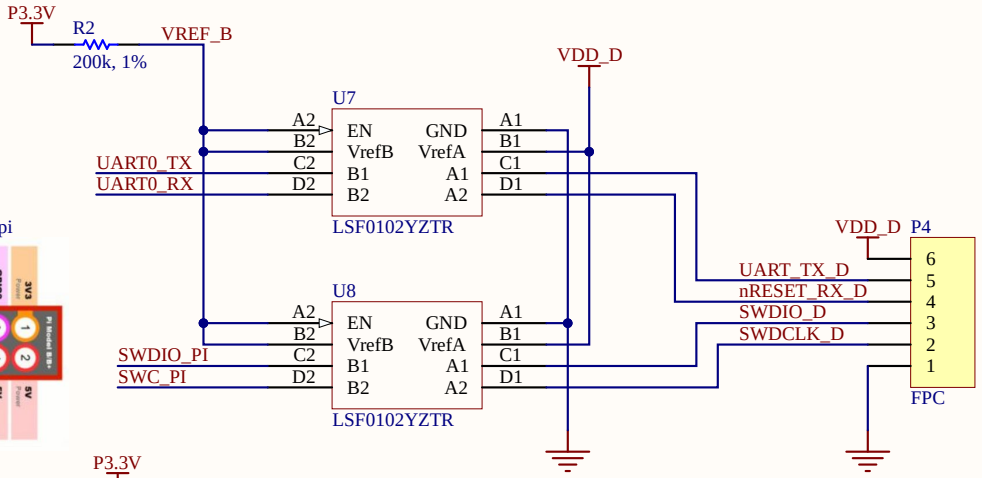
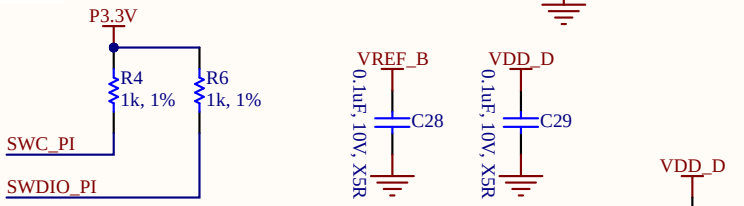
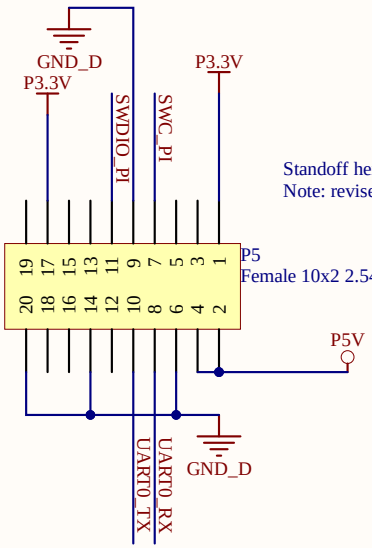


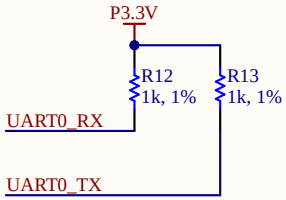
Rpi Vertical Stack Header
Debug & control







Standoff height is 8.51mm
Note: revised footprint is female (flipped at footprint level, not symbol)



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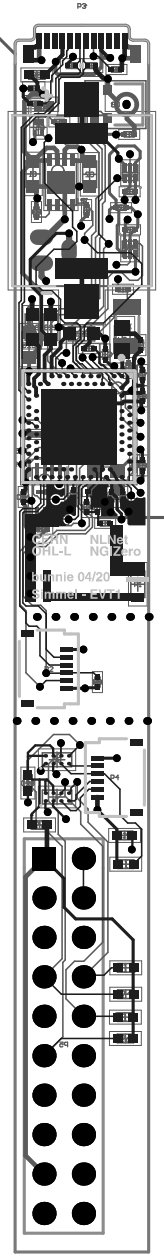
Route outline along midline



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 2	PP-006	0.071mm	4.1	
2	Layer 1	Copper	0.035mm		
	Dielectric 1	FR-4	0.500mm	4.8	
3	Layer 2	Copper	0.035mm		
	Dielectric 3	PP-006	0.071mm	4.1	
4	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				
Total board thickness:			0.804mm		

Solder mask green
Silkscreen white
Finish ENIG

Target 0.145mm to 50 ohm in stack